



## Product Change Notification: MAAN-07VGQN798

### Date:

14-Feb-2025

### Product Category:

Memory

### Notification Subject:

CCB 7401 Final Notice: Qualification of palladium-coated copper with gold flash (CuPdAu) as a new wire material and G631BQF as a new mold compound material for AT24C32D-MAHM-T, AT24C32D-MAHM-E, AT24C32E-MAHM-T, AT24C64D-MAHM-T and AT24C64D-MAHM-E catalog part numbers (CPN) available in 8L UDFN (2x3x0.6mm) package assembled at ATP7 assembly site.

### Affected CPNs:

**[MAAN-07VGQN798\\_Affected\\_CPN\\_02142025.pdf](#)**  
**[MAAN-07VGQN798\\_Affected\\_CPN\\_02142025.csv](#)**

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of palladium-coated copper with gold flash (CuPdAu) as a new wire material and G631BQF as a new mold compound material for AT24C32D-MAHM-T, AT24C32D-MAHM-E, AT24C32E-MAHM-T, AT24C64D-MAHM-T and AT24C64D-MAHM-E catalog part numbers (CPN) available in 8L UDFN (2x3x0.6mm) package assembled at ATP7 assembly site.

### Pre and Post Summary Changes:

	Pre Change		Post Change	
Assembly Site	Microchip Technology Thailand	Amkor Technology Philippines (P3/P4), INC.	Microchip Technology Thailand	Amkor Technology Philippines

	(MMT)	(ATP7)	(MMT)	(P3/P4), INC. (ATP7)
<b>Wire Material</b>	CuPdAu	PdCu	CuPdAu	CuPdAu
<b>Die Attach Material</b>	8600	CRM-1085A or AMK-06	8600	AMK-06
<b>Molding Compound Material</b>	G700LTD	G700Y	G700LTD	G631BQF
<b>Lead-Frame Material</b>	EFTEC-64T	C7025	EFTEC-64T	C7025

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability by qualifying CuPdAu as a new wire material and G631BQF as a new mold compound material.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 31 March 2025 (date code: 2514)

**Note Below EFSD:** Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Timetable Summary:**

	February 2025					March 2025				
<b>Work Week</b>	05	06	07	08	09	10	11	12	13	14
<b>Qual Report Availability</b>			x							
<b>Final PCN Issue Date</b>			x							

Estimated Implementation Date										X
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**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** February 14, 2025: Issued final notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

### Attachments:

**PCN\_MAAN-07VGQN798 Qual Report-ATP7.pdf**

**PCN\_MAAN-07VGQN798 Qual Report-MMT.pdf**

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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